

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free):   XC9801xxxxDR-G  
Typical Mass:           10     mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	1.296	Silicon	129600	7440-21-3
	-	Arsenic	8	7440-38-2
Lead pad	2.365	Nickel	236500	7440-02-0
	0.108	Silver	10800	7440-22-4
	0.024	Gold	2400	7440-57-5
Die attach	0.069	Silver	6900	7440-22-4
	0.018	Epoxy Resin	1800	—
	0.005	Phenol Resin	500	—
Bonding wire	0.095	Gold	9500	7440-57-5
Resin	5.267	Silica	526700	60676-86-0
	0.301	Epoxy Resin	30100	—
	0.271	Phenol Resin	27100	—
	0.181	Metal Hydroxide	18100	—

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."